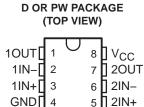
SLCS141D - MAY 2003 - REVISED APRIL 2008

- Qualified for Automotive Applications
- ESD Protection Exceeds 1000 V Per MIL-STD-883, Method 3015; Exceeds 100 V Using Machine Model (C = 200 pF, R = 0)
- Single Supply or Dual Supplies
- Low Supply-Current Drain Independent of Supply Voltage . . . 0.4 mA Typ Per Comparator
- Low Input Bias Current . . . 25 nA Typ
- Low Input Offset Current . . . 5 nA Typ
- Low Input Offset Voltage . . . 2 mV Typ
- Common-Mode Input Voltage Range Includes Ground

- Differential Input Voltage Range Equal to Maximum-Rated Supply Voltage . . . ±36 V
- Low Output Saturation Voltage
- Output Compatible With TTL, MOS, and CMOS



description/ordering information

This device consists of two independent voltage comparators that are designed to operate from a single power supply over a wide range of voltages. Operation from dual supplies is possible, as long as the difference between the two supplies is 2 V to 36 V, and V_{CC} is at least 1.5 V more positive than the input common-mode voltage. Current drain is independent of the supply voltage. The outputs can be connected to other open-collector outputs to achieve wired-AND relationships.

The LM2903Q is tested from -40°C to 125°C and is manufactured to demanding automotive requirements.

ORDERING INFORMATION†

TA	V _{IO} max AT 25°C	MAX V _{CC}	PACKAGE [‡] ORDERABLE PART NUMBER			TOP-SIDE MARKING
-40°C to 125°C	7 mV	30 V	SOIC (D)	Tape and reel	LM2903QDRQ1	2903Q1
	7 mV	30 V	TSSOP (PW)	Tape and reel	LM2903QPWRQ1	2903Q1
	7 mV	32 V	SOIC (D)	Tape and reel	LM2903VQDRQ1	2903VQ1
	7 mV	32 V	TSSOP (PW)	Tape and reel	LM2903VQPWRQ1	2903VQ1
	2 mV	32 V	SOIC (D)	Tape and reel	LM2903AVQDRQ1	2903AVQ
	2 mV	32 V	TSSOP (PW)	Tape and reel	LM2903AVQPWRQ1	2903AVQ

[†] For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI web site at http://www.ti.com.

symbol (each comparator)





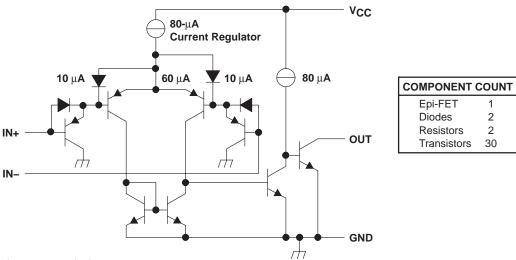
Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



[‡]Package drawings, thermal data, and symbolization are available at http://www.ti.com/packaging.

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schematic (each comparator)



Current values shown are nominal.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage, V _{CC} (see Note 1)	36 V
Differential input voltage, V _{ID} (see Note 2)	
Input voltage range, V _I (either input)	\dots –0.3 V to 36 V
Output voltage, VO	36 V
Output current, IO	20 mA
Duration of output short-circuit to ground (see Note 3)	Unlimited
Package thermal impedance, θ _{JA} (see Note 4): D package	97°C/W
PW package	149°C/W
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds: D or PW package	260°C
Storage temperature range, T _{stg}	-65° C to 150° C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. All voltage values, except differential voltages, are with respect to GND.
 - 2. Differential voltages are at IN+ with respect to IN-.
 - 3. Short circuits from outputs to V_{CC} can cause excessive heating and eventual destruction.
 - 4. The package thermal impedance is calculated in accordance with JESD 51-7.



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electrical characteristics at specified free-air temperature, V_{CC} = 5 V (unless otherwise noted)

	PARAMETER	TEST CONDITION	s	T _A †	MIN	TYP	MAX	UNIT	
			Non A dovisoo	25°C		2	7	mV	
,,	lanut effect voltage	$V_0 = 1.4 \text{ V},$	Non-A devices	Full range			15		
VIO	Input offset voltage	$V_{IC} = V_{IC}(min),$ $V_{CC} = 5 V \text{ to MAX}$	A-suffix devices	25°C		1	2		
				Full range			4		
1	lanut effect comment	V- 44V		25°C		5	50	^	
lio	Input offset current	V _O = 1.4 V		Full range			200	nA	
	In a state of the	V 44V		25°C		-25	-250	nA	
lΒ	Input bias current	$V_0 = 1.4 \text{ V}$		Full range			-500		
Common-mode				25°C	0 to V _{CC} -1.5			,	
VICR	VICR input voltage range§		Full range	0 to V _{CC} -2			V		
AVD	Large-signal differential-voltage amplification	$V_{CC} = 15 \text{ V},$ $V_{O} = 1.4 \text{ V to } 11.4 \text{ V},$ $R_{L} \ge 15 \text{ k}\Omega \text{ to } V_{CC}$		25°C	25	100		V/mV	
	High-level	V _{OH} = 5 V	V _{ID} = 1 V	25°C		0.1	50	nA	
ЮН	output current	VOH = VCC MAX‡	Full range			1	μΑ		
.,	Low-level			25°C		150	400		
VOL output voltage		$I_{OL} = 4 \text{ mA},$	$V_{ID} = -1 V$	Full range			700	mV	
l _{OL}	Low-level output current	V _{OL} = 1.5 V,	V _{ID} = -1 V	25°C	6			mA	
loo	Supply ourrent	D	V _{CC} = 5 V	25°C		0.8	1	mA	
Icc	Supply current	R _L = ∞	$V_{CC} = MAX^{\ddagger}$	Full range			2.5	IIIA	

[†] Full range (MIN or MAX) for LM2903Q is -40°C to 125°C. All characteristics are measured with zero common-mode input voltage, unless otherwise specified.

switching characteristics, $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$

PARAMETER	TEST CONDITION	NS	TYP	UNIT
Response time	R _L connected to 5 V through 5.1 kΩ,	100-mV input step with 5-mV overdrive	1.3	
Response time	$C_L = 15 \text{ pF}^{\P}$, See Note 5	TTL-level input step	0.3	μs

[¶]C_L includes probe and jig capacitance.

NOTE 5: The response time specified is the interval between the input step function and the instant when the output crosses 1.4 V.



[‡] V_{CC} MAX = 30 V for non-V devices and 32 V for V-suffix devices.

[§] The voltage at either input or common-mode should not be allowed to go negative by more than 0.3 V. The upper end of the common-mode voltage range is V_{CC+} – 1.5 V, but either or both inputs can go to 30 V (32 V for V-suffix devices) without damage.





24-Jan-2013

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Top-Side Markings	Samples
LM2903AVQDRG4Q1	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	2903AVQ	Samples
LM2903AVQDRQ1	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	2903AVQ	Samples
LM2903AVQPWRG4Q1	ACTIVE	TSSOP	PW	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	2903AVQ	Samples
LM2903AVQPWRQ1	ACTIVE	TSSOP	PW	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	2903AVQ	Samples
LM2903QDRG4Q1	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	2903Q1	Samples
LM2903QDRQ1	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	2903Q1	Samples
LM2903QPWRG4Q1	ACTIVE	TSSOP	PW	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	2903Q1	Samples
LM2903QPWRQ1	ACTIVE	TSSOP	PW	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	2903Q1	Samples
LM2903VQDRG4Q1	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	2903VQ1	Samples
LM2903VQDRQ1	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	2903VQ1	Samples
LM2903VQPWRG4Q1	ACTIVE	TSSOP	PW	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	2903VQ	Samples
LM2903VQPWRQ1	ACTIVE	TSSOP	PW	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	2903VQ	Samples

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

TBD: The Pb-Free/Green conversion plan has not been defined.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.



PACKAGE OPTION ADDENDUM

24-Jan-2013

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes. **Pb-Free** (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL. Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

⁽⁴⁾ Only one of markings shown within the brackets will appear on the physical device.

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OTHER QUALIFIED VERSIONS OF LM2903-Q1:

Catalog: LM2903

NOTE: Qualified Version Definitions:

Catalog - TI's standard catalog product

D (R-PDSO-G8)

PLASTIC SMALL OUTLINE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AA.



D (R-PDSO-G8)

PLASTIC SMALL OUTLINE



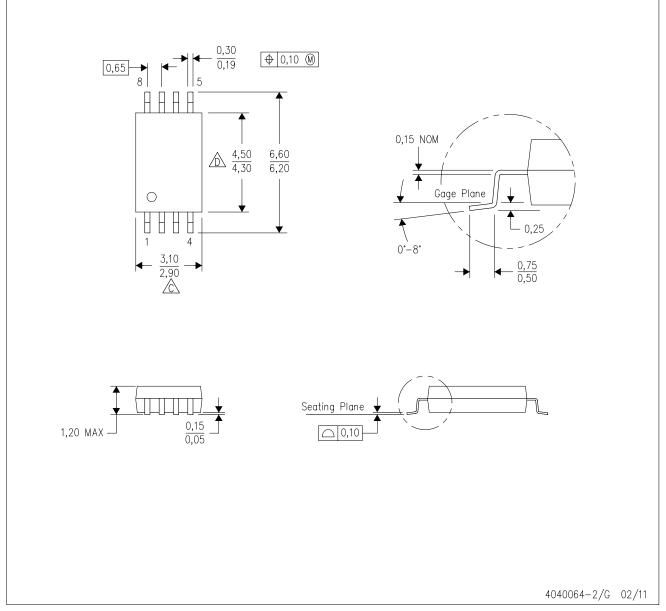
NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



PW (R-PDSO-G8)

PLASTIC SMALL OUTLINE



NOTES:

- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M—1994.
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
- E. Falls within JEDEC MO-153



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